Product / Package Information

Package	LFCSP - Side Solderable
Body Size (mm)	5 X 5 X 0.75 (3.6 EP)
Lead Count	32
Terminal Finish	100 Sn
MS Number	MS010739C

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.29E-02	86.20	862000	38.13	381258
Thermosets	Epoxy resin	Proprietary	1.59E-03	6.00	60000	2.65	26538
Thermosets	Phenol resin	Proprietary	1.59E-03	6.00	60000	2.65	26538
Other inorganic materials	Metal Hydroxide	Proprietary	3.99E-04	1.50	15000	0.66	6634
Other inorganic materials	Carbon black	1333-86-4	7.97E-05	0.30	3000	0.13	1327
Subtotal			2.66 E-02	100.00	1000000	44.23	442294

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.82 E-02	97.5	975000	46.89	468896
Copper & its alloys	Iron	7439-89-6	6.79 E-04	2.35	23500	1.13	11302
Copper & its alloys	Zinc	7440-66-6	3.47 E-05	0.12	1200	0.06	577
Copper & its alloys	Phosphorus	7723-14-0	8.67 E-06	0.03	300	0.01	144
Subtotal			2.89 E-02	100.00	1000000	48.09	480919

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.89 E-04	100.0	1000000	0.48	4809

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.69 E-03	100.0	1000000	2.81	28061

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.22 E-04	100.0	1000000	0.54	5352

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.03 E-03	100.0	1000000	3.38	33823

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.10 E-04	73.54	735400	0.35	3487
Other organic materials	Epoxy resin A	TS ref# 10013	2.09 E-05	7.35	73500	0.03	348
Others	Anhydride	TS ref# 10181	2.09 E-05	7.35	73500	0.03	348
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	8.38 E-06	2.94	29400	0.01	139
Other organic materials	Epoxy resin B	TS ref# 10237	8.38 E-06	2.94	29400	0.01	139
Others	Epoxy resin modifier	TS ref# 10038	8.38 E-06	2.94	29400	0.01	139
Others	Anhydride	TS ref# 10180	8.38 E-06	2.94	29400	0.01	139
Subtotal			2.85 E-04	100.0	1000000	0.47	4741

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.01 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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